

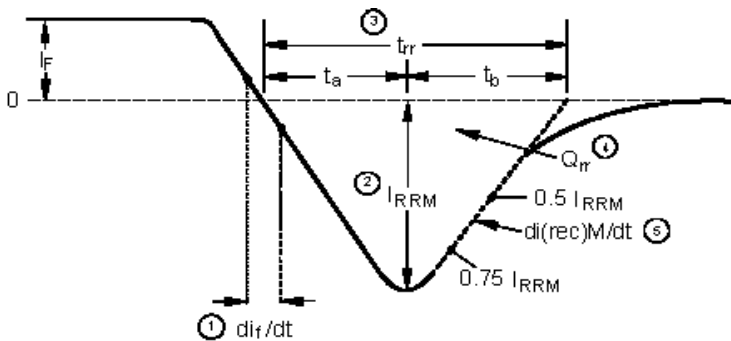


PRELIMINARY SPECIFICATION №142. **ULTRAFAST DIODE KD-1560UF.**

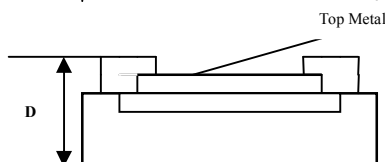
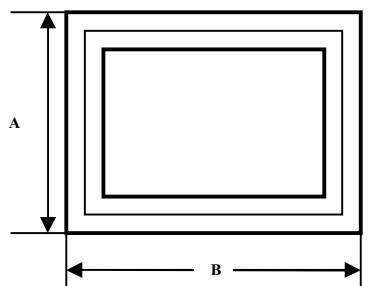
 VSP MIKRON 		15A/600V. Die Size- 2.92*3.94mm.		
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=0,10mA$	V_B	V	600	620
Average Rectified Forward Current	$I_{F(AV)}$	A	15,0	-
DC Forward Voltage @ $25^\circ C, I_F=15,0A$	V_F	V	1,35	1,3
Maximum Reverse Current @ $25^\circ C, V_R=600V$ $125^\circ C, V_R=600V$	I_R	MA	0,010 0,500	0,009 0,450
Reverse Recovery Time, $I_F=1A, V_R=30V, di_F/dt=100A/uS.$	t_{rr}	nS	65	60
Operating Junction Temperature	T_J	$^\circ C$	175	



- di_F/dt - Rate of change of current through zero crossing
- I_{RRM} - Peak reverse recovery current
- t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current
- Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}
- $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

DIM	ITEM	μm
A	Die Size	2920
B	Top Metal Size	3940
D	Thickness	350max.
Scribe line Width		60



Top metal: Al – for Wire Bonding.

Backside metal: Ti-Ni-Ag – for Soldering.

www.vsp-mikron.com